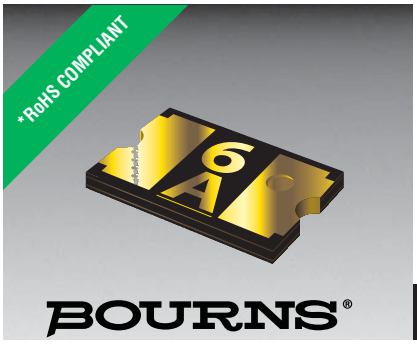


Features

- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Small footprint size (1210)
- RoHS compliant* and halogen free**
- Agency recognition*

Applications

- Game consoles
- PC motherboards
- USB port protection - USB 2.0, 3.0 & OTG
- HDMI 1.4 Source protection
- IEEE 1394 ports
- Mobile phones
- Digital cameras

MF-USMF Series - PTC Resettable Fuses

Electrical Characteristics

Model	V max. Volts	I max. Amps	I_{hold}	I_{trip}	Resistance		Max. Time To Trip		Tripped Power Dissipation
			Amperes at 23 °C		Ohms at 23 °C		Amperes at 23 °C	Seconds at 23 °C	Watts at 23 °C
			Hold	Trip	$R_{Min.}$	$R_{1Max.}$			Typ.
MF-USMF005	30	10	0.05	0.15	2.800	50.000	0.25	1.50	0.6
MF-USMF010	30	10	0.10	0.30	0.800	15.000	0.50	0.60	0.6
MF-USMF020	30	10	0.20	0.40	0.400	5.000	8.00	0.02	0.6
MF-USMF035	6	40	0.35	0.75	0.200	1.300	8.00	0.20	0.6
MF-USMF050	13.2	40	0.50	1.00	0.180	0.900	8.00	0.10	0.6
MF-USMF075	6	40	0.75	1.50	0.070	0.450	8.00	0.10	0.6
MF-USMF110	6	40	1.10	2.20	0.050	0.210	5.00	1.00	0.6
MF-USMF150	6	40	1.50	3.00	0.030	0.110	5.00	5.00	0.6
MF-USMF175X***	6	40	1.75	3.50	0.020	0.090	8.00	1.00	0.7

*** CSA approval pending.

Environmental Characteristics

Operating Temperature	-40 °C to +85 °C	
Maximum Device Surface Temperature in Tripped State	125 °C	
Passive Aging	+85 °C, 1000 hours	±5 % typical resistance change
Humidity Aging	+85 °C, 85 % R.H. 1000 hours	±5 % typical resistance change
Thermal Shock	+85 °C to -40 °C, 20 times	±10 % typical resistance change
Solvent Resistance	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-883C, Method 2007.1, Condition A	No change

Test Procedures And Requirements For Model MF-USMF Series

Test	Test Conditions	Accept/Reject Criteria
Visual/Mech.	Verify dimensions and materials	Per MF physical description
Resistance	In still air @ 23 °C	Rmin ≤ R ≤ R1max
Time to Trip	At specified current, Vmax, 23 °C	T ≤ max. time to trip (seconds)
Hold Current	30 min. at Ihold	No trip
Trip Cycle Life	Vmax, Imax, 100 cycles	No arcing or burning
Trip Endurance	Vmax, 48 hours	No arcing or burning
Solderability	ANSI/J-STD-002	95 % min. coverage

UL File Number	E174545 http://www.ul.com/ Follow link to Certifications, then UL File No., enter E174545
CSA File Number	CA110338 http://directories.csa-international.org/ Under “Certification Record” and “File Number” enter 110338-0-000
TÜV Certificate Number	R 02057213 http://www.tuvdotcom.com/ Follow link to “other certificates”, enter File No. 2057213

*RoHS Directive 2002/95/EC Jan 27 2003 including Annex.

**To be considered halogen free, each homogenous material can have a maximum concentration of 900 ppm of either bromine or chlorine.

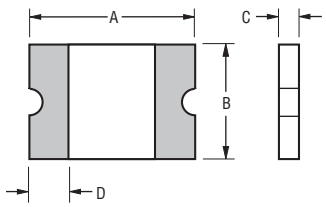
Product Dimensions

Model	A		B		C		D
	Min.	Max.	Min.	Max.	Min.	Max.	Min.
MF-USMF005	3.00 (0.118)	3.43 (0.135)	2.35 (0.093)	2.80 (0.110)	0.80 (0.031)	1.1 (0.043)	0.30 (0.012)
MF-USMF010	3.00 (0.118)	3.43 (0.135)	2.35 (0.093)	2.80 (0.110)	0.80 (0.031)	1.1 (0.043)	0.30 (0.012)
MF-USMF020	3.00 (0.118)	3.43 (0.135)	2.35 (0.093)	2.80 (0.110)	0.80 (0.031)	1.1 (0.043)	0.30 (0.012)
MF-USMF035	3.00 (0.118)	3.43 (0.135)	2.35 (0.093)	2.80 (0.110)	0.55 (0.022)	0.85 (0.033)	0.30 (0.012)
MF-USMF050	3.00 (0.118)	3.43 (0.135)	2.35 (0.093)	2.80 (0.110)	0.55 (0.022)	0.85 (0.033)	0.30 (0.012)
MF-USMF075	3.00 (0.118)	3.43 (0.135)	2.35 (0.093)	2.80 (0.110)	0.55 (0.022)	0.85 (0.033)	0.30 (0.012)
MF-USMF110	3.00 (0.118)	3.43 (0.135)	2.35 (0.093)	2.80 (0.110)	0.55 (0.022)	0.85 (0.033)	0.30 (0.012)
MF-USMF150	3.00 (0.118)	3.43 (0.135)	2.35 (0.093)	2.80 (0.110)	0.40 (0.016)	0.85 (0.033)	0.30 (0.012)
MF-USMF175X	3.00 (0.118)	3.43 (0.135)	2.35 (0.093)	2.80 (0.110)	0.40 (0.016)	0.85 (0.033)	0.30 (0.012)

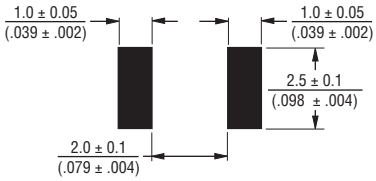
Packaging: 3000 pcs. per reel.

DIMENSIONS: MM (INCHES)

Top and Bottom View *Side View*



Recommended Pad Layout

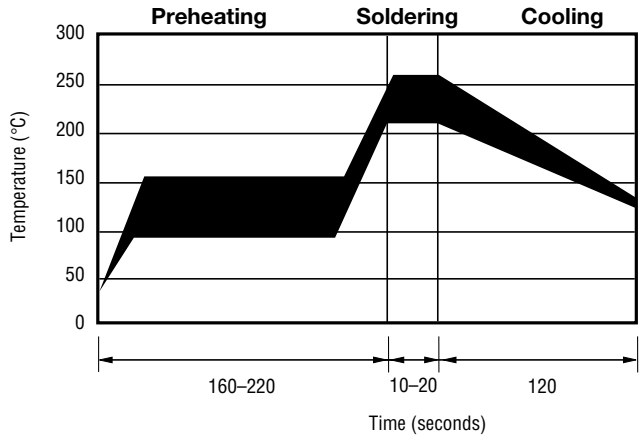


Terminal material:
Electroless Ni under immersion Au

Termination pad solderability:
Standard Au finish:
Meets ANSI/J-STD-002 Category 2.

Recommended Storage:
40 °C max./70 % RH max.

Solder Reflow Recommendations



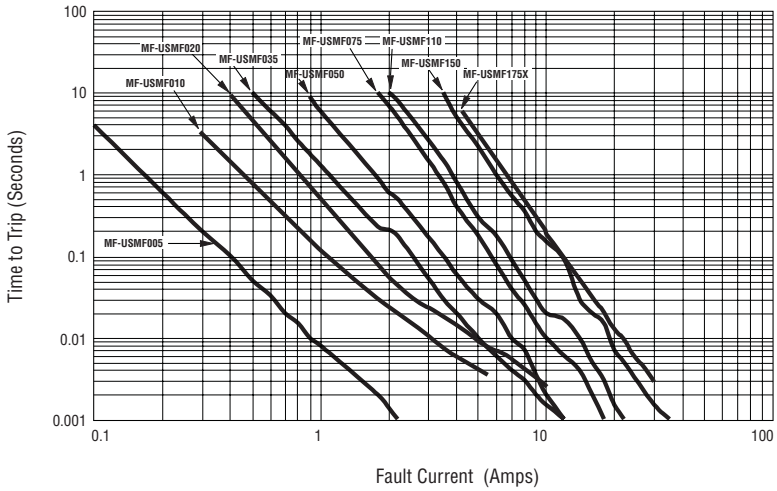
Notes:

- MF-USMF models cannot be wave soldered.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Compatible with Pb and Pb-free solder reflow profiles.
- Excess solder may cause a short circuit, especially during hand soldering. Please refer to the Multifuse® Polymer PTC Soldering Recommendation guidelines.

Thermal Derating Chart - I_{hold} (Amps)

Model	Ambient Operating Temperature								
	-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C
MF-USMF005	0.08	0.07	0.06	0.05	0.04	0.04	0.03	0.03	0.02
MF-USMF010	0.15	0.13	0.12	0.10	0.09	0.08	0.07	0.06	0.05
MF-USMF020	0.32	0.28	0.24	0.20	0.18	0.16	0.14	0.12	0.10
MF-USMF035	0.51	0.46	0.40	0.34	0.30	0.27	0.24	0.22	0.18
MF-USMF050	0.76	0.66	0.58	0.48	0.42	0.38	0.35	0.29	0.23
MF-USMF075	1.10	0.97	0.86	0.72	0.64	0.58	0.55	0.47	0.39
MF-USMF110	1.60	1.42	1.26	1.10	0.94	0.86	0.80	0.70	0.58
MF-USMF150	2.30	2.02	1.76	1.43	1.24	1.11	1.00	0.85	0.65
MF-USMF175X	2.80	2.45	2.10	1.75	1.55	1.45	1.35	1.25	1.10

Typical Time to Trip at 23 °C



The Time to Trip curves represent typical performance of a device in a simulated application environment. Actual performance in specific customer applications may differ from these values due to the influence of other variables.

How to Order

MF - USMF 010 X - 2

Multifuse® Product Designator

Series
USMF = 1210 Surface Mount Component

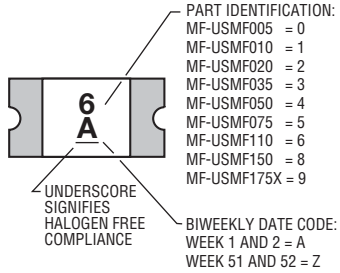
Hold Current, Ihold
005-175 (0.05-1.75 Amps)

Multifuse® freeXpansion™ Design

Packaging
Packaged per EIA 481-1
-2 = Tape and Reel

Typical Part Marking

Represents total content. Layout may vary.



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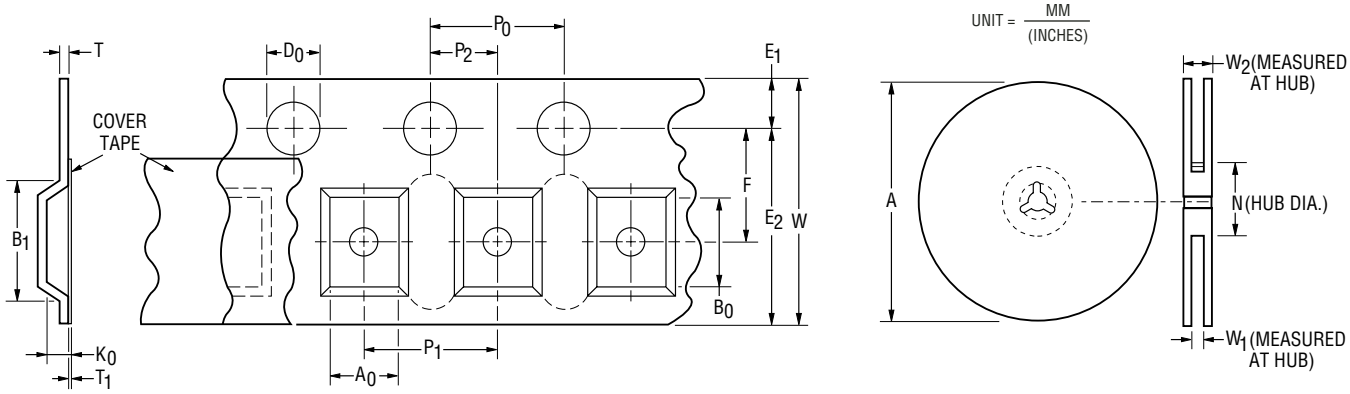
Europe: TEL +41-41 7685555 • FAX +41-41 7685510
The Americas: TEL +1-951 781-5500 • FAX +1-951 781-5700
www.bourns.com

MF-USMF Series Tape and Reel Specifications

BOURNS®

Tape Dimensions	MF-USMF Series per EIA 481-2
W	8.0 ± 0.3 (0.315 ± 0.012)
P_0	4.0 ± 0.1 (0.157 ± 0.004)
P_1	4.0 ± 0.1 (0.157 ± 0.004)
P_2	2.0 ± 0.05 (0.079 ± 0.002)
A_0	2.76 ± 0.10 (0.109 ± 0.004)
B_0	3.50 ± 0.10 (0.138 ± 0.004)
B_1 max.	4.35 (0.171)
D_0	1.5 + 0.1/-0.0 (0.059 + 0.004/-0)
F	3.5 ± 0.05 (0.138 ± 0.002)
E_1	1.75 ± 0.10 (0.069 ± 0.004)
E_2 min.	6.25 (0.246)
T max.	0.6 (0.024)
T_1 max.	0.1 (0.004)
K_0	1.07 ± 0.10 (0.042 ± 0.004)
Leader min.	390 (15.35)
Trailer min.	160 (6.30)
Reel Dimensions	
A max.	185 (7.283)
N min.	50 (1.97)
W_1	8.4 + 1.5/ -0.0 (0.331 + 0.059/-0.0)
W_2 max.	14.4 (0.567)



Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001
Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

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http://moschip.ru/get-element

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